AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-9 (canceled).

Claim 10 (new): A ceramic multilayer substrate comprising:

a ceramic laminate including a plurality of ceramic layers, having a first main surface, and including internal circuit elements disposed inside of the laminate;

a resin layer having a bonding surface in contact with the first main surface of the ceramic laminate and a mounting surface opposite to the bonding surface;

external electrodes, each disposed on the mounting surface of the resin layer and electrically connected to at least one of the internal circuit elements of the ceramic laminate; and

at least one of a ground electrode, a dummy electrode, and a capacitor electrode disposed at an interface between the first main surface of the ceramic laminate and the bonding surface of the resin layer.

Claim 11 (new): The ceramic multilayer substrate according to Claim 10, wherein the at least one of the ground electrode, the dummy electrode and the capacitor electrode includes a sintered metal that is integral with the ceramic laminate.

Claim 12 (new): The ceramic multilayer substrate according to Claim 10, further comprising a first circuit component mounted on the first main surface and covered with the resin layer, wherein the at least one of the ground electrode, the dummy electrode and the capacitor electrode are disposed on a side that is closer to the mounting surface than the first circuit component.

Claim 13 (new): The ceramic multilayer substrate according to Claim 12, wherein the first circuit component is disposed within a region defined by projecting the at least one of the ground electrode, the dummy electrode and the capacitor electrode on the first main surface.

Claim 14 (new): The ceramic multilayer substrate according to Claim 10, further comprising relay electrodes disposed so as to extend along the first main surface, wherein electrical connections from the external electrodes to the internal circuit elements are provided through the relay electrodes.

Claim 15 (new): The ceramic multilayer substrate according to Claim 10, wherein the ceramic laminate comprises a second main surface on an opposite side to the first main surface, and a second circuit component is mounted on the second main surface.

Claim 16 (new): The ceramic multilayer substrate according to Claim 15, wherein a conductive case is disposed on the second main surface to cover the second circuit component.

Claim 17 (new): The ceramic multilayer substrate according to Claim 15, wherein the second circuit component on the second main surface is covered with a molded resin layer.

Claim 18 (new): A ceramic multilayer substrate comprising:

a ceramic laminate including a plurality of ceramic layers, having a first main surface, and including internal circuit elements disposed inside of the laminate;

a resin layer having a bonding surface in contact with the first main surface of the ceramic laminate and a mounting surface opposite to the bonding surface;

external electrodes, each disposed on the mounting surface of the resin layer and electrically connected to at least one of the internal circuit elements of the ceramic laminate;

a ground electrode disposed at an interface between the first main surface of the ceramic laminate and the bonding surface of the resin layer; and

a capacitor electrode facing the ground electrode from a side opposite to the mounting surface such that a capacitor is defined by the ground electrode and the capacitor electrode.

Claim 19 (new): The ceramic multilayer substrate according to Claim 18, further comprising relay electrodes disposed so as to extend along the first main surface, wherein electrical connections from the external electrodes to the internal circuit elements are provided through the relay electrodes.

Claim 20 (new): The ceramic multilayer substrate according to Claim 18, wherein the ceramic laminate comprises a second main surface on an opposite side to the first main surface, and a second circuit component is mounted on the second main surface.

Claim 21 (new): The ceramic multilayer substrate according to Claim 20, wherein a conductive case is disposed on the second main surface to cover the second circuit component.

Claim 22 (new): The ceramic multilayer substrate according to Claim 20, wherein the second circuit component on the second main surface is covered with a molded resin layer.

Claim 23 (new): A ceramic multilayer substrate comprising:

a ceramic laminate including a plurality of ceramic layers, having a first main surface, and including internal circuit elements disposed inside of the laminate;

a resin layer having a bonding surface in contact with the first main surface of the ceramic laminate and a mounting surface opposite to the bonding surface;

external electrodes, each disposed on the mounting surface of the resin layer and electrically connected to at least one of the internal circuit elements of the ceramic laminate; and

at least one of a ground electrode, a dummy electrode, and a capacitor electrode disposed inside of the resin layer.

Claim 24 (new): The ceramic multilayer substrate according to Claim 23, wherein the at least one of the ground electrode, the dummy electrode and the capacitor electrode includes a sintered metal integrally baked with the ceramic laminate.

Claim 25 (new): The ceramic multilayer substrate according to Claim 23, further comprising a first circuit component mounted on the first main surface and covered with the resin layer, wherein the at least one of the ground electrode, the dummy electrode and the capacitor electrode are disposed on a side that is closer to the mounting surface than the first circuit component.

Claim 26 (new): The ceramic multilayer substrate according to Claim 25, wherein the first circuit component is disposed within a region defined by projecting the at least one of the ground electrode, the dummy electrode and the capacitor electrode on the first main surface.

Claim 27 (new): The ceramic multilayer substrate according to Claim 23, further comprising relay electrodes disposed so as to extend along the first main surface, wherein electrical connections from the external electrodes to the internal circuit elements are provided through the relay electrodes.

Claim 28 (new): The ceramic multilayer substrate according to Claim 23, wherein the ceramic laminate comprises a second main surface on an opposite side to the first main surface, and a second circuit component is mounted on the second main surface.

Claim 29 (new): The ceramic multilayer substrate according to Claim 28, wherein a conductive case is disposed on the second main surface to cover the second circuit component.

Claim 30 (new): The ceramic multilayer substrate according to Claim 28, wherein the second circuit component on the second main surface is covered with a molded resin layer.

Claim 31 (new): A ceramic multilayer substrate comprising:

a ceramic laminate including a plurality of ceramic layers, having a first main surface, and including internal circuit elements disposed inside of the laminate;

a resin layer having a bonding surface in contact with the first main surface of the ceramic laminate and a mounting surface opposite to the bonding surface;

external electrodes, each disposed on the mounting surface of the resin layer and electrically connected to at least one of the internal circuit elements of the ceramic laminate;

a ground electrode disposed inside of the resin layer; and

a capacitor electrode facing the ground electrode from a side opposite to the mounting surface such that a capacitor is defined by the ground electrode and the capacitor electrode.

Claim 32 (new): The ceramic multilayer substrate according to Claim 31, further comprising relay electrodes disposed so as to extend along the first main surface, wherein electrical connections from the external electrodes to the internal circuit

elements are provided through the relay electrodes disposed so as to extend along the first main surface.

Claim 33 (new): The ceramic multilayer substrate according to Claim 31, wherein the ceramic laminate comprises a second main surface on an opposite side to the first main surface, and a second circuit component is mounted on the second main surface.

Claim 34 (new): The ceramic multilayer substrate according to Claim 33, wherein a conductive case is disposed on the second main surface to cover the second circuit component.

Claim 35 (new): The ceramic multilayer substrate according to Claim 31, wherein the second circuit component on the second main surface is covered with a molded resin layer.